

Sintering carrier with  
DBC mastercard.



Sintering carrier with  
single substrates.

## PiNK application and R&D services For soldering and sintering technology

Within a rapidly increasing and competitive market, fast process developments with highest yield and reliability are needed to satisfy the ever-growing demands for modern electronic devices.

With its application and R&D services PiNK supports its customers from the very beginning of packaging development to series production. Starting with equipment demonstrations, soldering and sintering trials, PiNK provides feasibility studies of new packaging concepts incl. package assembly.

PiNK also evaluates and improves UPH, yield and quality. Essential process know-how is given to the customer's engineers and technicians by trainings. In case of process issues PiNK offers continuous support.

### Range of services

- Consulting and concept development
- Trials and demonstrations for customers
- Feasibility studies
- Prototype assembly
- Process development
- Process training and support

### Applications for soldering/sintering

- Die-attach
- Substrate to baseplate
- Die top side connection
- Double-sided packaging
- Multi-layer packaging

### PiNK equipment

- VADU soldering systems
- Sintering system SIN 200+
- Plasma cleaning equipment

### Additional equipment

- Pick & place machine
- Stencil printer

### Test devices

- Test DBCs with Au, Ag, Cu metallization
- Dummy Si chips
- Leadframes

### In-house quality inspection

- Microscopy
- Mandrel-bending test
- Surface tension measurement
- IR camera

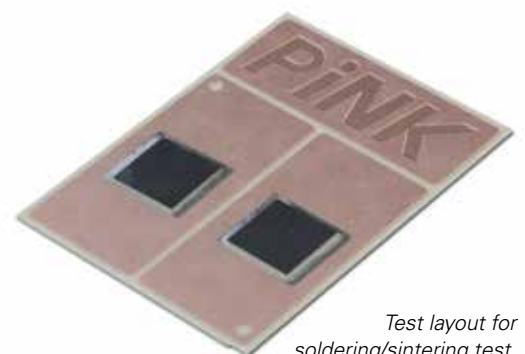
### External analysis

- X-Ray
- C-SAM
- Shear-tests
- Cross sectioning
- REM/EDX analysis

### PiNK GmbH

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Test layout for  
soldering/sintering test.